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DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: **Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, And Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit**, Serial No. 09/449,025, filed November 24, 1999.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under

Section 1001 of Title 18 of the United States Code and that such willful false statement may jeopardize the validity of the application or any patent issued therefrom.

* * * * *

Full name of inventor: Shozo Nagano

Inventor's Signature: Shozo Nagano

Date: 2/1/2000

Residence: Kanagawa, Japan

Citizenship: Japanese

Post Office Address: 1-3-5-405 Mizuhiki Atsugi
Kanagawa, ~~Japan 234-004~~
243-0004 Japan

* * * * *

Full name of inventor: Hinrich Hargarter

Inventor's Signature: _____

Date: _____

Residence: The Netherlands

Citizenship: German

Post Office Address: P.O. Box 10000
1970 CA IJmuiden
The Netherlands

* * * * *

Full name of inventor: **Jianxing Li**

Inventor's Signature: _____

Date: _____

Residence: **Spokane, Washington**

Citizenship: **Chinese**

Post Office Address: **4908 N. Calvin Road
Spokane, WA 99216**

* * * * *

Full name of inventor: **Jane Buehler**

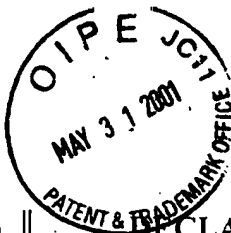
Inventor's Signature: _____

Date: _____

Residence: **Spokane, Washington**

Citizenship: **U.S.**

Post Office Address: **18517 E. Norman Ridge Lane
Spokane, WA 99217**



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4 * * * * *

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6 Inventor's Signature: _____

7 Date: _____

8 Residence: Kanagawa, Japan

9 Citizenship: Japanese

10 Post Office Address: 1-3-5-405 Mizuhiki Atsugi
11 Kanagawa, Japan 234-004

12 * * * * *

13 Full name of inventor: Hinrich Hargarter

14 Inventor's Signature: Hinrich Hargarter

15 Date: 02-15-00

16 Residence: The Netherlands

17 Citizenship: German

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19 1970 CA IJmuiden
20 The Netherlands
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* * * * *

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Inventor's Signature: _____

Date: _____

Residence: **Spokane, Washington**

Citizenship: **Chinese**

Post Office Address: **4908 N. Calvin Road
Spokane, WA 99216**

* * * * *

Full name of inventor: **Jane Buehler**

Inventor's Signature: _____

Date: _____

Residence: **Spokane, Washington**

Citizenship: **U.S.**

Post Office Address: **18517 E. Norman Ridge Lane
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4 * * * * *

5 Full name of inventor: **Shozo Nagano**

6 Inventor's Signature: _____

7 Date: _____

8 Residence: **Kanagawa, Japan**

9 Citizenship: **Japanese**

10 Post Office Address: **1-3-5-405 Mizuhiki Atsugi**
Kanagawa, Japan 234-004

12 * * * * *

13 Full name of inventor: **Hinrich Hargarter**

14 Inventor's Signature: _____

15 Date: _____

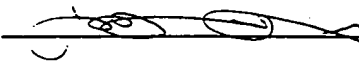
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1970 CA IJmuiden
19 **The Netherlands**

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Full name of inventor: **Jianxing Li**

Inventor's Signature: 

Date: 4/27/00


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Full name of inventor: **Jane Buehler**

Inventor's Signature: 

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